

STP 1413

Mechanical Properties of Structural Films

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Contents

Overview	vii
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FRACTURE AND FATIGUE OF STRUCTURAL FILMS

Surface Topology and Fatigue in Si MEMS Structures —S. M. ALLAMEH, B. GALLY, S. BROWN, AND W. O. SOBOYEJO	3
Cross Comparison of Direct Strength Testing Techniques on Polysilicon Films — D. A. LAVAN, T. TSUCHIYA, G. COLES, W. G. KNAUSS, I. CHASIOTIS, AND D. READ	16
Fatigue and Fracture in Membranes for MEMS Power Generation —D. F. BAHR, B. T. CROZIER, C. D. RICHARDS, AND R. F. RICHARDS	28
Effects of Microstructure on the Strength and Fracture Toughness of Polysilicon: A Wafer Level Testing Approach —R. BALLARINI, H. KAHN, N. TAYEBI, AND A. H. HEUER	37
Fatigue Crack Growth of a Ni-P Amorphous Alloy Thin Film —K. TAKASHIMA, M. SHIMOJO, Y. HIGO, AND M. V. SWAIN	52
Direct Tension and Fracture Toughness Testing Using the Lateral Force Capabilities of a Nanomechanical Test System —D. A. LAVAN, K. JACKSON, B. MCKENZIE, S. J. GLASS, T. A. FRIEDMANN, J. P. SULLIVAN, AND T. E. BUCHHEIT	62
Fracture Behavior of Micro-Sized Specimens with Fatigue Pre-Crack Prepared from a Ni-P Amorphous Alloy Thin Film —K. TAKASHIMA, M. SHIMOJO, Y. HIGO, AND M. V. SWAIN	72

ELASTIC BEHAVIOR AND RESIDUAL STRESS IN THIN FILMS

Integrated Platform for Testing MEMS Mechanical Properties at the Wafer Scale by the IMaP Methodology —M. P. DE BOER, N. F. SMITH, N. D. MASTERS, M. B. SINCLAIR, AND E. J. PRYPUTNIEWICZ	85
Influence of the Film Thickness on Texture, Residual Stresses and Cracking Behavior of PVD Tungsten Coatings Deposited on a Ductile Substrate —T. GANNE, G. FARGES, J. CREPIN, R.-M. PRADEILLES-DUVAL, AND A. ZAOUÏ	96
High Accuracy Measurement of Elastic Constants of Thin Films by Surface Brillouin Scattering —M. G. BEGHI, C. E. BOTTANI, AND R. PASTORELLI	109
Effect of Nitrogen Feedgas Addition on the Mechanical Properties of Nano-Structured Carbon Coatings —S. A. CATLEDGE AND Y. K. VOHRA	127
Characterization of the Young's Modulus of CMOS Thin Films —N. HOSSAIN, J. W. JU, B. WARNEKE, AND K. S. J. PISTER	139
Derivation of Elastic Properties of Thin Films from Measured Acoustic Velocities — R. PASTORELLI, S. TARANTOLA, M. G. BEGHI, C. E. BOTTANI, AND A. SALTELLI	152
Side-by-Side Comparison of Passive MEMS Strain Test Structures under Residual Compression —N. D. MASTERS, M. P. DE BOER, B. D. JENSEN, M. S. BAKER, AND D. KOESTER	168

TENSILE TESTING OF STRUCTURAL FILMS

Mechanical Tests of Free-Standing Aluminum Microbeams for MEMS Application— P. ZHANG, H.-J. LEE, AND J. C. BRAVMAN	203
Tensile Testing of Thin Films Using Electrostatic Force Grip— T. TSUCHIYA AND J. SAKATA	214
Tensile Tests of Various Thin Films— W. N. SHARPE, JR., K. M. JACKSON, G. COLES, M. A. EBY, AND R. L. EDWARDS	229
Ductile Thin Foils of Ni₃Al— M. DEMURA, K. KISHIDA, O. UMEZAWA, E. P. GEORGE, AND T. HIRANO	249
Microstructural and Mechanical Characterization of Electrodeposited Gold Films— G. S. LONG, D. T. READ, J. D. MCCOLSKEY, AND K. CRAGO	262
Determining the Strength of Brittle Thin Films for MEMS— G. C. JOHNSON, P. T. JONES, M.-T. WU, AND T. HONDA	278

THERMOMECHANICAL, WEAR, AND RADIATION DAMAGE OF STRUCTURAL FILMS

Thermomechanical Characterization of Nickel-Titanium-Copper Shape Memory Alloy Films— K. P. SEWARD, P. B. RAMSEY, AND P. KRULEVITCH	293
Deformation and Stability of Gold/Polysilicon Layered MEMS Plate Structures Subjected to Thermal Loading— M. L. DUNN, Y. ZHANG, AND V. M. BRIGHT	306
The Effects of Radiation on the Mechanical Properties of Polysilicon and Polydiamond Thin Films— R. L. NEWTON AND J. L. DAVIDSON	318
Index	329